



YM-HST-1000-PRO

High Speed

High Temperature

Large Format

Build Volume : 1000×1000×1000 mm

Printing Temperature : Up to 450°C

Hot Bed Temperature : Up to 120°C

Chamber Temperature : Up to 70°C

Filament Box Temperature : Up to 70°C

Extrusion System : IDEX Dual Extruder Modularization

Majority of the Materials on Market :

High Performance : PEEK,CF-PEEK,GF-PEEK,PEKK,PPS(Size within 150mm)

Engineering : PA, CF-PA, GF-PA, PC, CF-PC, ABS, CF-ABS, PETG, CF-PETG, CF-PET, ASA, GF-ASA, PLA, CF-PLA, TPU

Support: HT-SP, E-REMOVE, E-WATER

Item	YM-HST-1000-PRO
Printing Size (L × B × H)	1000×1000×1000 mm
Machine Size (L × B × H)	2027×1660×1694 mm
Packing Size (L × B × H)	2230×1860×2070 mm
Net Weight	900KG
Gross Weight	1000KG
Warning light (Height)	345mm
Power	200~250 V, 50~60 Hz 11600 W

Common	Principle: Printing Temperature: HotBed Temperature: Chamber Temperature: Filament Box Temperature: Extrusion System: Filament Diameter: Filament Box Capacity: Positioning Accuracy: Printing Speed: Printing Platform: Heated Bed Materials: Platform Auto Calibration: Power Failure Recovery: Filament Absent Warning: Plug Detection: Supporting Materials: Layer Thickness: Nozzle Diameter: Connection Control: Suggest Operating Environment: Storage Temperature: Technology Certification: Air Filter:	Fused Filament Fabrication 450 °C 120°C 70°C 70°C Idex Dual Extruder Modularization 1.75 mm 3Kg ×2 (Total 2 Reels) X/Y: 5.86 μm Z: 1.56 μm 0 - 400 mm/s (Max speed is tested by PLA) Vacuum adsorption Platform Silicon Support Support Support Support High Performance : PEEK,CF-PEEK,GF-PEEK,PEKK,PPS(Size within 150mm) Engineering : PA, CF-PA, GF-PA, PC, CF-PC, ABS, CF-ABS, PETG, CF-PETG, CF-PET, ASA, GF-ASA, PLA, CF-PLA, TPU Support: HT-SP, E-REMOVE, E-WATER 0.05 – 0.4mm 0.6 mm(standard),0.4 mm, 0.8mm ,1.0mm Ethernet, USB2.0, WIFI 10-40°C, relatively humidity 10-90%, No Moisture Condensation -25 - 55 °C, relatively humidity 10-90%, No Moisture Condensation CE, RoHS Filter HEPA, grade H13, minimum filter particle 0.3 μ m. Filtering efficiency 99.95%
Printer Control	Screen: Resolution: Motion Control Chip: Logic Control Chip: Display control chip: Flash Memory: Memory: Firmware: Operating System:	10.1 Inch color touch screen 1280 x 800 STM32 ARM Cortex M4 168 MHz Allwinnertech H6 64 Bits ARM Cortexm-A53 quad-core 1.8GHz GPU Mali T720 2GB 16GB High speed firmware based on secondary development of KLIPPER Embedded Linux
Software	Slicing software: computer system: input format: output format:	IEMAI 3D EXPERT, Cura, Simplify3D,Prusa Windows 64 Bit STL, OBJ, 3MF GCODE

Features	<p> Idex Dual Extruder Modularization Copy & Mirror Printing Support & Dual Color Printing CAN Communication Between Extruder And System Automatic leveling sensor for nozzle pressure Extruder with built-in acceleration sensor High-Speed Printing Power Failure Recovery Filament Absent Warning Plug Detection Automatic Shutdown Vacuum Adsorption Platform Internal and external heating dual zone of hot bed Independent heating of dual zone of filament box Simultaneous heating of dual zone of chamber XY axis FOC servo motor drive Z-axis high-power dual stepper motor drive XYZ axis full linear guide rail guidance XY axis synchronous belt drive Z-axis ball screw drive Built in negative pressure vacuum pump with a vacuum capacity of 125L Three color indicator light for device status The X motion frame can be quickly replaced, achieving particle printing+CNC cutting function (optional, additional purchase required) </p>
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